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FDBL0110N60

### January 2016

# N-Channel PowerTrench<sup>®</sup> MOSFET 60 V, 300 A, 1.1 m $\Omega$

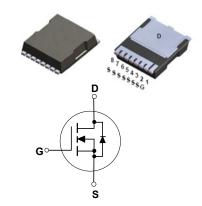
### **Features**

- Typical  $R_{DS(on)}$  = 0.85 m $\Omega$  at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- Typical  $Q_{g(tot)}$  = 170 nC at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- UIS Capability
- RoHS Compliant

### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.ht-ml?id=PN PSOFA-008

### **MOSFET Maximum Ratings** $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter		Ratings	Units
$V_{DSS}$	Drain-to-Source Voltage		60	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
I <sub>D</sub>	Drain Current - Continuous (V <sub>GS</sub> =10) (Note 1)	T <sub>C</sub> = 25°C	300	^
	Pulsed Drain Current	T <sub>C</sub> = 25°C	See Figure 4	A
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	1167	mJ
В	Power Dissipation		429	W
$P_D$	Derate Above 25°C		2.86	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

#### Notoo

- 1: Current is limited by bondwire configuration.
- 2: Starting  $T_J = 25$  °C, L = 0.57mH,  $I_{AS} = 64$ A,  $V_{DD} = 40$ V during inductor charging and  $V_{DD} = 0$ V during time in avalanche.
- 3: R<sub>0,JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0,JC</sub> is guaranteed by design, while R<sub>0,JA</sub> is determined by the board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

### **Package Marking and Ordering Information**

Device Marking	Device	Package			
FDBL0110N60	FDBL0110N60	MO-299A	-	-	-

Units

Max.

Тур.

### **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

**Parameter** 

Off Characteristics							
B <sub>VDSS</sub>	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$ ,	V <sub>GS</sub> = 0V	60	-	-	V
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> = 60V	$T_J = 25^{\circ}C$	-	-	1	μΑ
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
looo	Gate-to-Source Leakage Current	V <sub>00</sub> = +20V	,	_	_	+100	nΔ

**Test Conditions** 

Min.

### **On Characteristics**

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
В	Resistance	I <sub>D</sub> = 80A,	$T_{J} = 25^{\circ}C$	-	0.85	1.1	$m\Omega$
NDS(on)		V <sub>GS</sub> = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	1.5	2.2	$m\Omega$

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	.,	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz		13650	-	pF
C <sub>oss</sub>	Output Capacitance				3375	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112			255	-	pF
$R_g$	Gate Resistance	f = 1MHz	f = 1MHz		2.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to 10V	V <sub>DD</sub> = 48V	-	170	220	nC
Q <sub>g(th)</sub>	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I <sub>D</sub> = 80A	-	24	32	nC
$Q_{gs}$	Gate-to-Source Gate Charge		_	-	56	-	nC
$Q_{qd}$	Gate-to-Drain "Miller" Charge			-	24	-	nC

### **Switching Characteristics**

t <sub>on</sub>	Turn-On Time	$V_{DD}$ = 30V, $I_{D}$ = 80A, $V_{GS}$ = 10V, $R_{GEN}$ = $6\Omega$	-	-	137	ns
t <sub>d(on)</sub>	Turn-On Delay		-	45	1	ns
t <sub>r</sub>	Rise Time		-	61	-	ns
t <sub>d(off)</sub>	Turn-Off Delay		-	80	-	ns
t <sub>f</sub>	Fall Time		-	41	-	ns
t <sub>off</sub>	Turn-Off Time		ı	ı	156	ns

### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Sour	Maximum Continuous Drain to Source Diode Forward Current			300	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	See Figure 4	Α
V <sub>SD</sub> So	Source-to-Drain Diode Voltage	I <sub>SD</sub> =80A, V <sub>GS</sub> = 0V	-	-	1.25	V
	Source-to-Drain Diode Voltage	$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
t <sub>rr</sub>	Reverse-Recovery Time	$I_F = 80A$ , $dI_{SD}/dt = 100A/\mu s$ ,	-	107	139	ns
Q <sub>rr</sub>	Reverse-Recovery Charge	V <sub>DD</sub> =48V	-	183	265	nC

#### Note:

4: The maximum value is specified by design at  $T_J$  = 175°C. Product is not tested to this condition in production.

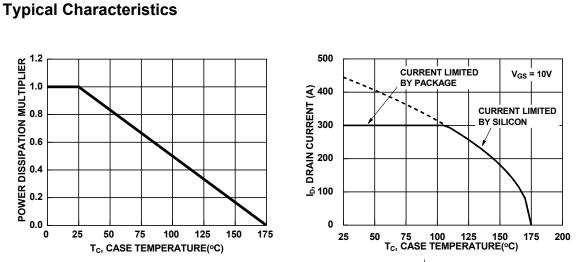
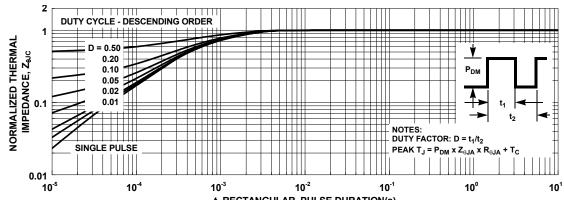


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

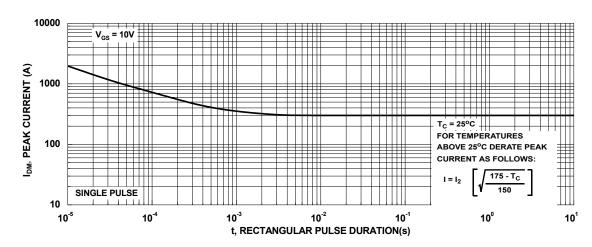


Figure 4. Peak Current Capability

### **Typical Characteristics**

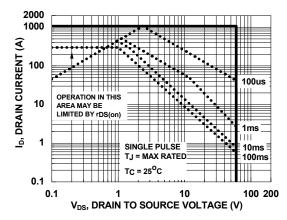
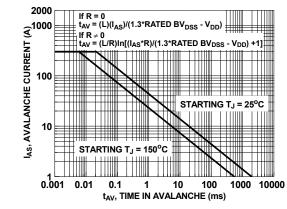


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

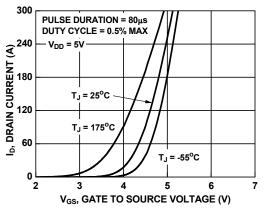


Figure 7. Transfer Characteristics

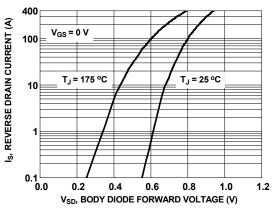


Figure 8. Forward Diode Characteristics

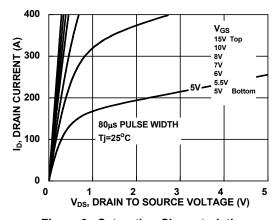


Figure 9. Saturation Characteristics

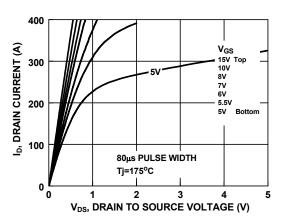
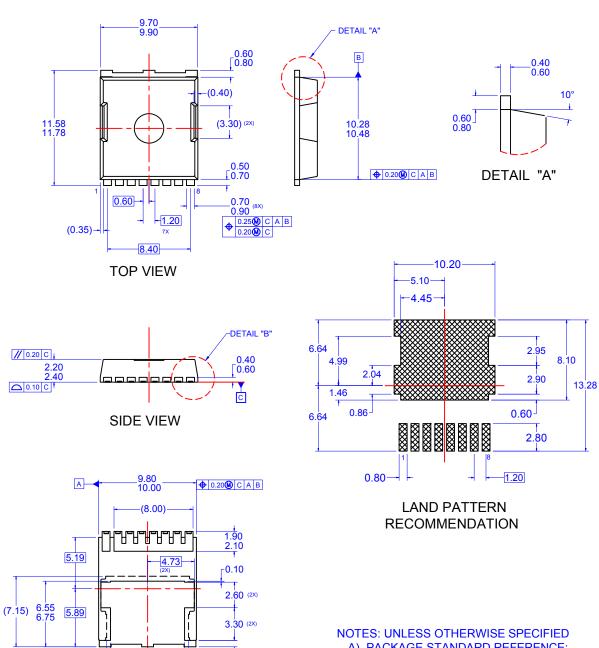
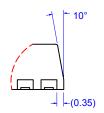


Figure 10. Saturation Characteristics



- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

- - 1.20 0.65-3.75 7.60 -(8.30) **BOTTOM VIEW** 



DETAIL "B"

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